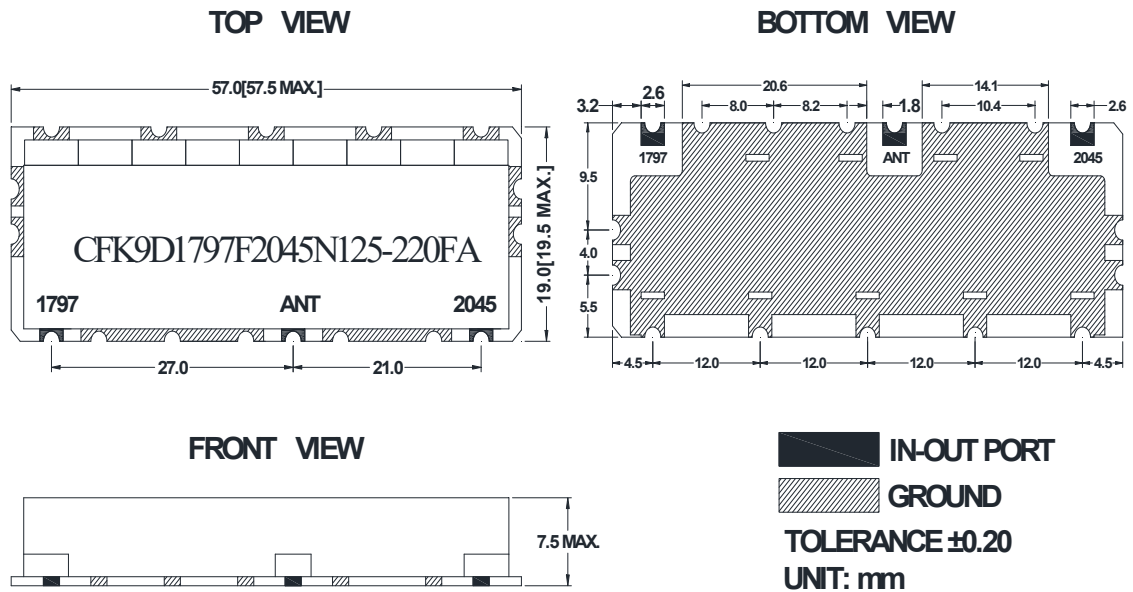


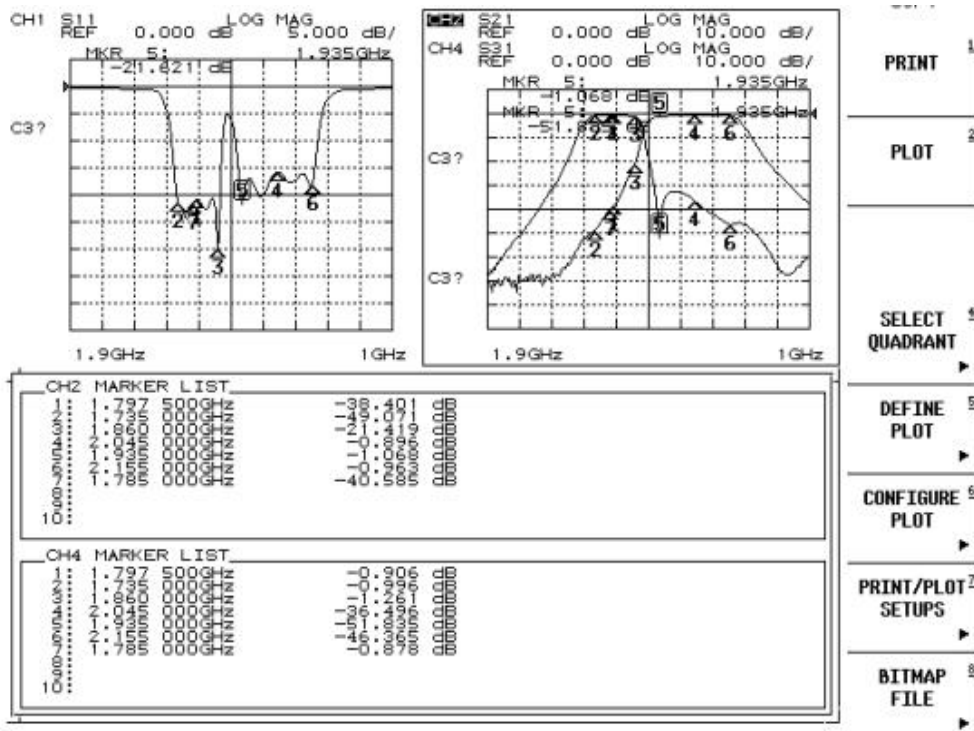
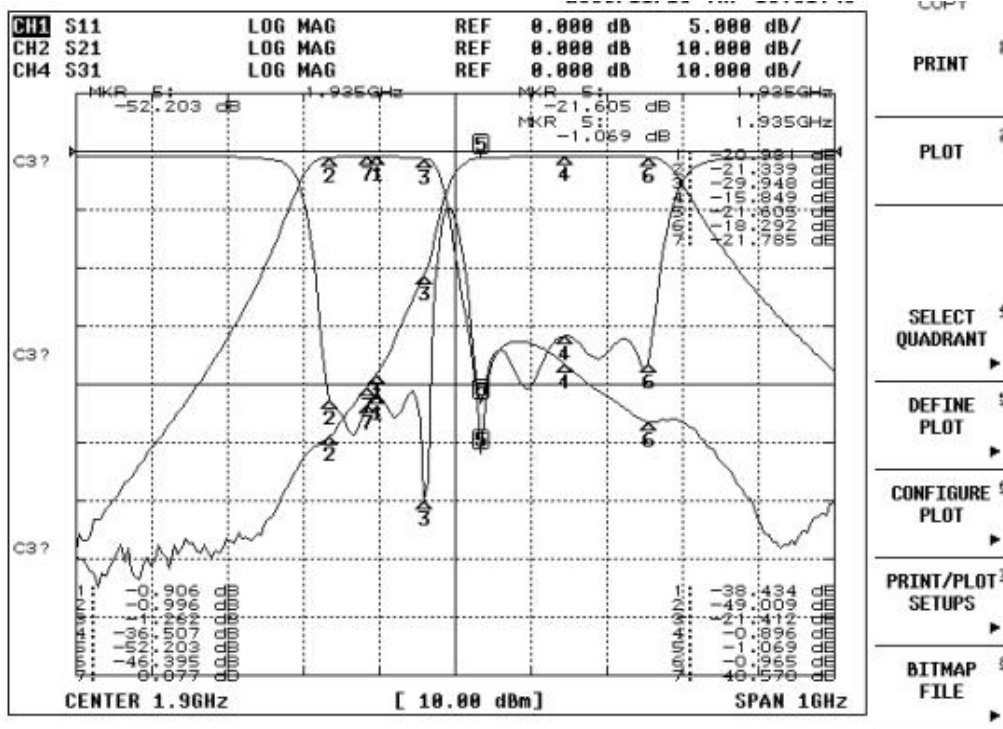
## Electrical Specification

ITEMS	ANT >> Low	ANT >> High	UNIT
Center Frequency [fo]	1797.5	2045.0	MHz
Bandwidth [BW]	fo ±62.5 [1736.0~1860.0]	fo ±110.0 [1935.0~2155.0]	MHz
Insertion Loss in BW	2.0	2.0	dB max
Ripple in BW	1.0	1.0	dB max
Return Loss in BW	15.0	15.0	dB min
Attenuation <input checked="" type="checkbox"/> Absolute Value <input type="checkbox"/> Relative Value	40 dBmin. @ [1935.0~ ]	40dBmin.@ [1785.0~ ]	MHz
	dBmin. @ [ ~ ]	dBmin. @ [ ~ ]	MHz
	dBmin. @ [ ~ ]	dBmin. @ [ ~ ]	MHz
	dBmin. @ [ ~ ]	dBmin. @ [ ~ ]	MHz
Group Delay Variation			ns max
Input Power	3.0		W max.
In/Out Impedance	50 Ω		
Operation Temperature Range	-40°C to +85°C		

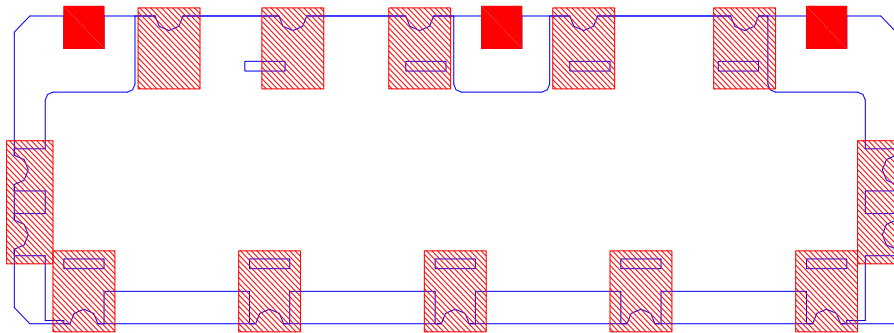
## Mechanical Specification



## Plot Data

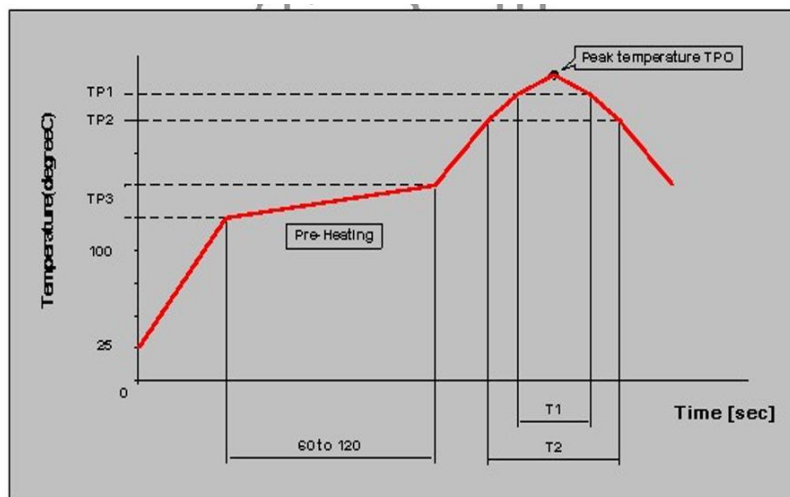


## Recommneded PC Board Pattern



 **IN-OUT PORT SOLDERING POINT**  
 **GROUND SOLDERING POINT**

## Soldering Condition



Measuring point of temperature : IN-OUT Terminals of The Device

Reflow Soldering : Both Convection and Infrared Rays, Hot Air and Hot Plate

Reflow standard condition	TPO (°C)	TP1 (°C)	T1 (s)	TP2 (°C)	T2 (s)	TP3 (°C)
Sn-3Ag-0.5 solder	245±5	220	30 to 60	—	—	150 to 180
Test condition of reflow heat resistance	260±5/0	240	20	220	70	150 to 180